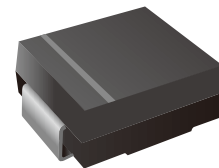


Surface Mount General Purpose Silicon Rectifier

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMC
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end

Ordering Information

Part Number	Shipping	Reel
LTS10AC THRU LTS10MC-TR3	3000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTS10AC	LTS10BC	LTS10DC	LTS10GC	LTS10JC	LTS10KC	LTS10MC	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	10							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	200							A
Maximum Instantaneous Forward Voltage at 10A	V_F	1.1							V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100							μA
Typical Junction Capacitance ⁽¹⁾	C_j	100							pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	10							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 cm X 5 cm) copper pad areas.



Characteristics Curves

Fig.1 Forward Current Derating Curve

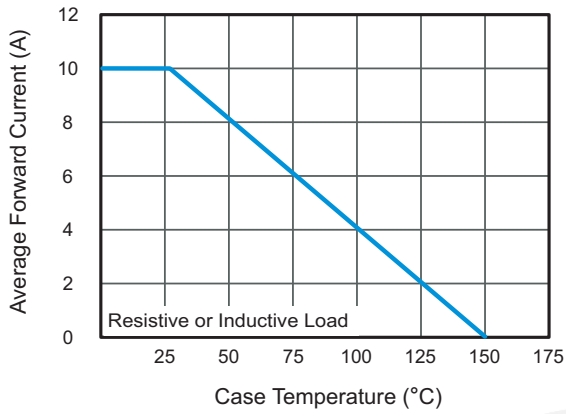


Fig.2 Typical Reverse Characteristics

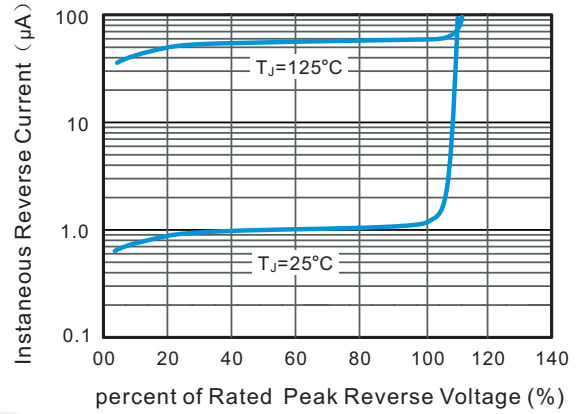


Fig.3 Typical Forward Characteristic

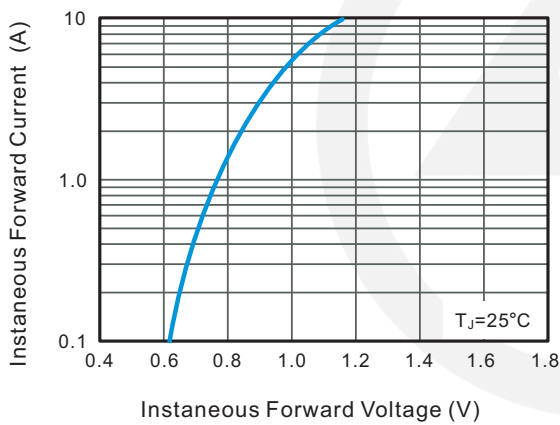


Fig.4 Typical Junction Capacitance

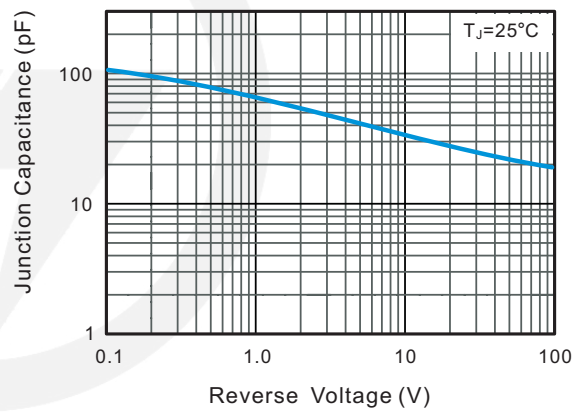
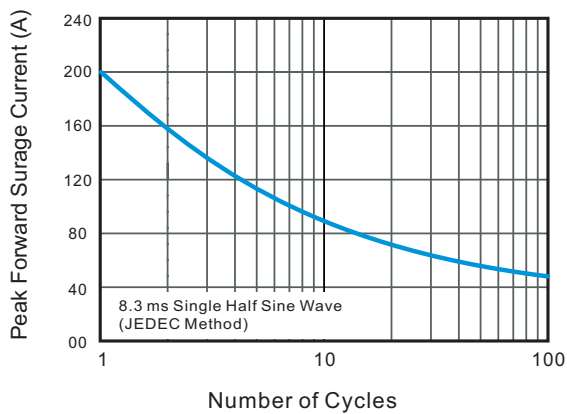
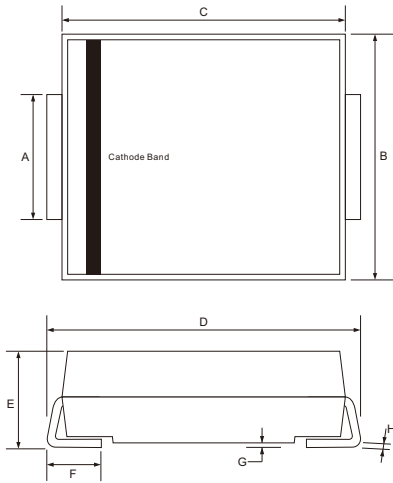


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



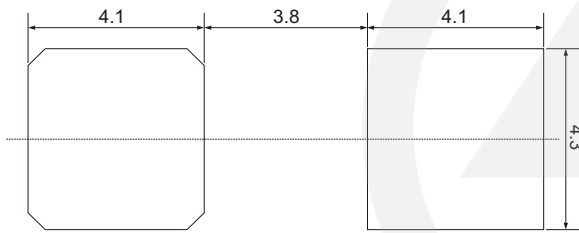
SMC Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	2.75	3.27
B	5.59	6.22
C	6.50	7.11
D	7.60	8.13
E	1.99	2.80
F	0.76	1.60
G	0.05	0.31
H	0.10	0.31

SMC Suggested Pad Layout



Note:

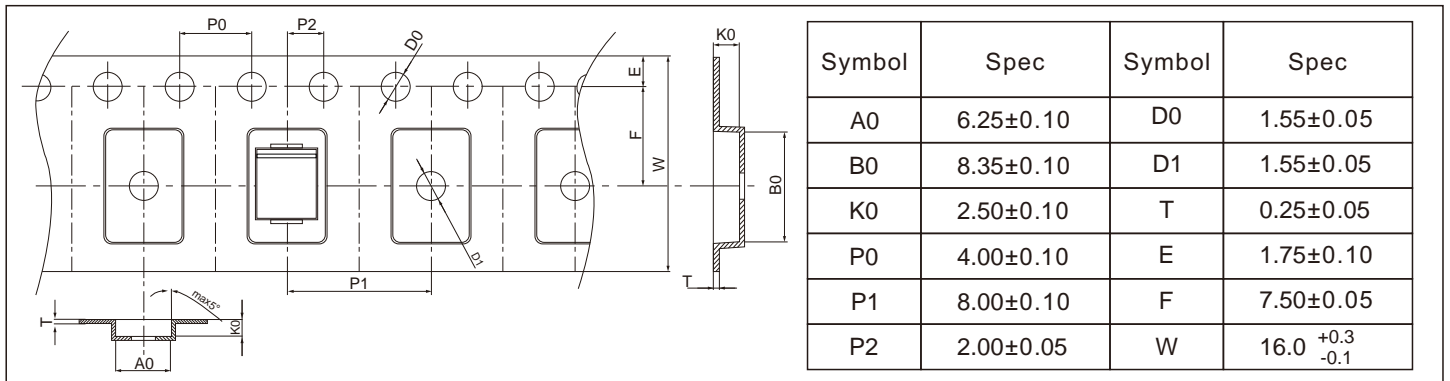
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Marking

Type number	Marking code
LTS10AC	S10A
LTS10BC	S10B
LTS10DC	S10D
LTS10GC	S10G
LTS10JC	S10J
LTS10KC	S10K
LTS10MC	S10M

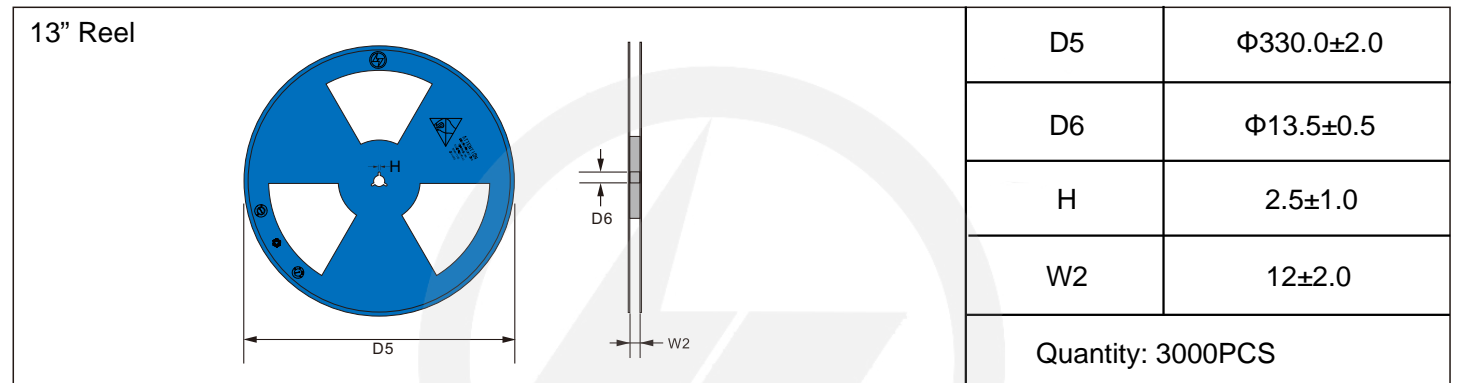
Carrier Tape Dimensions

Unit : mm

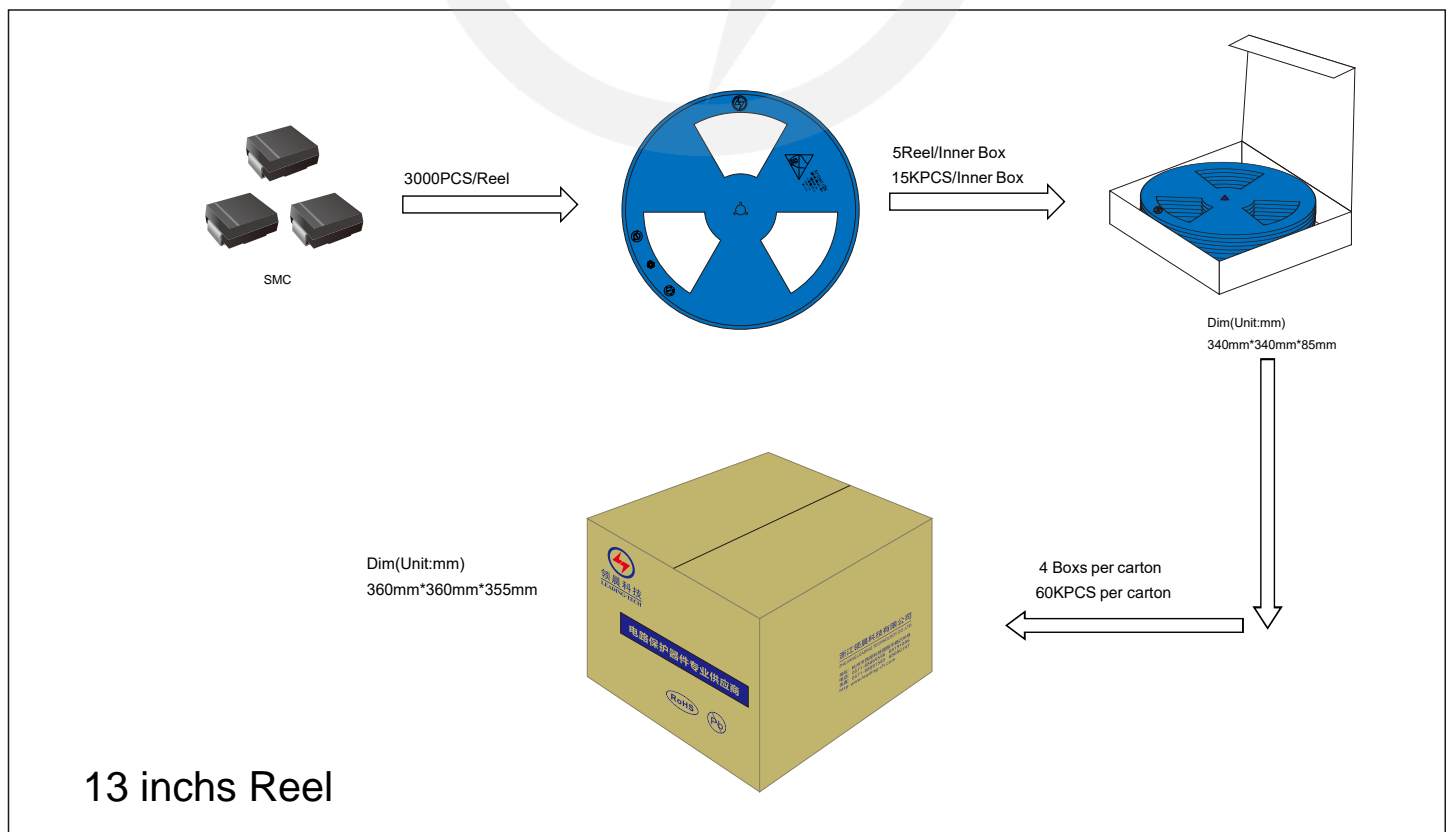


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2025.01.21	2025.01.21	3.0	New File	/	Ding	